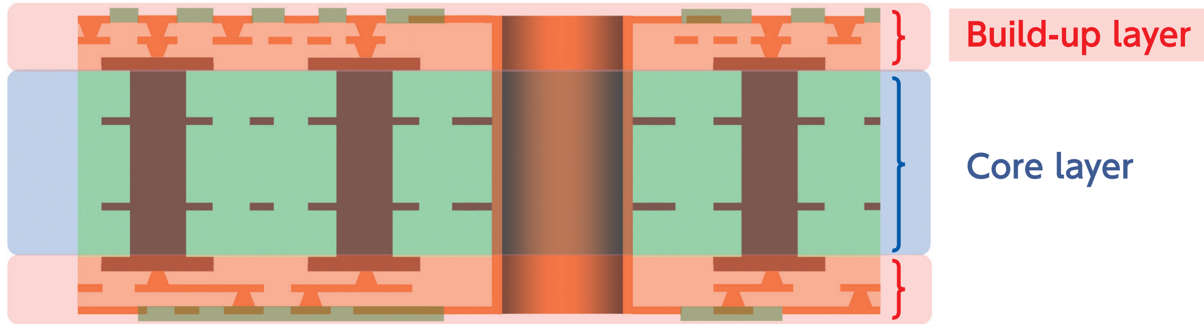
Acid copper plating additive for via filling

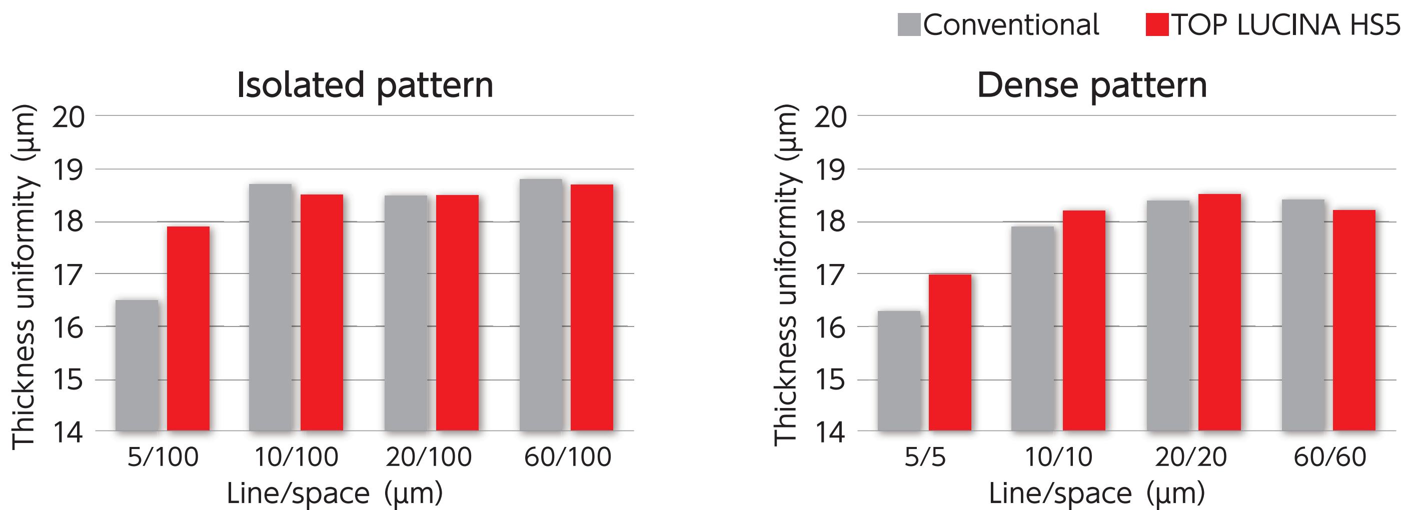
TOP LUCINA HS5

SAP

- For pattern plating to build-up layers to achieve thickness uniformity
- Realize operation at 2 to 3 A/dm²
- Control dome-shape occurrence for stacked via



High thickness uniformity for ultra-fine patterning



Control dome-shape occurrence in overfilling